

IN THE CLAIMS:

Claims 1-4 and 8-11 are presented for examination. Please amend claim 1 as indicated below. This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A device having:

a first wafer having a first area and a second area opposed to each other with a first scribe area in-between, wherein a first mechanical element and a first pad are formed in said first area and a second mechanical element and a second pad are formed in said second area, and

a second wafer which seals said first mechanical element and said second mechanical element with a prescribed space over each of said first mechanical element and said second mechanical element formed in said first wafer, wherein:

said second wafer is provided with a through-hole having a first side and a second side opposed to said first side, for exposing said first pad and said second pad, and

said through-hole is so positioned that said first pad is placed between said first side and said first scribe area and said second pad is placed between said second side and said first scribe area, and

wherein said first pad and said second pad are overlapped with said through-hole when viewed in a plan view.

2. (Previously Presented) The device according to Claim 1, wherein:

said first wafer has a second scribe area and a third scribe area,

said through-hole has a third side crossing said first side and said second side and a fourth side opposed to said third side,

the fourth side of said through-hole is placed between said second scribe area, said first pad and said second pad, and

the third side of said through-hole is arranged to be placed between said third scribe area, said first pad and said second pad.

3. (Previously Presented) The device according to Claim 1, wherein:

said first wafer has:

a second scribe area,
a third area opposed to said first area with said second scribe area in-between, and
a fourth area opposed to said second area with said second scribe area in-between
and opposed to said third area with said first scribe area in-between, wherein:

a third mechanical element and a third pad are formed in said third area,
a fourth mechanical element and a fourth pad are formed in said fourth area,
said through-hole is so arranged as to expose said third pad and said fourth pad,
and

said through-hole is so arranged as to place said third pad between said first side
and said first scribe area and to place said fourth pad between said second side and said
first scribe area.

4. (Previously Presented) The device according to Claim 3, wherein:

said through-hole has a third side crossing said first side and said second side and
a fourth side opposed to said third side,

said through-hole is so arranged as to place said first and second pads between
said third side and said second scribe area and to place said third and fourth pad between
said fourth side and said second scribe area.

- 5-7. (Canceled)

8. (Original) The device according to Claim 1, wherein:

said first wafer further has second through fifth scribe areas,
said first area is surrounded by said first, second, third and fourth scribe areas, and
said second area is surrounded by said first, second, third and fifth scribe areas.

9. (Original) The device according to Claim 8, wherein:

said first area is made a first chip by cutting said first, second, third and fourth
scribe areas, and

said second area is made a second chip by cutting said first, second, third and fifth
scribe areas.

10. (Original) The device according to Claim 3, wherein:
- said first wafer further has third through sixth scribe areas,
 - said first area is surrounded by said first, second, third and fourth scribe areas,
 - said second area is surrounded by said first, second, third and fifth scribe areas,
 - said third area is surrounded by said first, second, fourth and sixth scribe areas,
- and
- said fourth area is surrounded by said first, second, fifth and sixth scribe areas.
11. (Original) The device according to Claim 10, wherein:
- said first area is made a first chip by cutting said first, second, third and fourth scribe areas,
 - said second area is made a second chip by cutting said first, second, third and fifth scribe areas,
 - said third area is made a third chip by cutting said first, second, fourth and sixth scribe areas, and
 - said fourth area is made a fourth chip by cutting said first, second, fifth and sixth scribe areas.
- 12-26. (Cancelled)